

2814
PATENTO I P E
SEP 23 2002
PATENT & TRADEMARK OFFICE
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
AMENDMENT TRANSMITTAL LETTER

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to Commissioner of Patents and Trademarks, Washington, D.C. 20231 on September 16, 2002.

Renne M.F. Wyzykowski
Renne M.F. Wyzykowski

Applicant : Ende Shan
Application No. : 09/992,743
Filed : November 14, 2001
Title : LOW TEMPERATURE ALUMINUM PLANARIZATION PROCESS
Grp./Div. : 2814
Examiner : Ginette Peralta
Docket No. : 46890/DMC/V165

Assistant Commissioner for Patents
Washington, D.C. 20231

Post Office Box 7068
Pasadena, CA 91109-7068
September 16, 2002

Enclosed is an amendment to the above-identified application.

CLAIMS AS AMENDED						
	Claims Remaining After Amendment	Highest Number Paid For	Number Extra Claims	Small Entity Rate	Large Entity Rate	FEE
Total Claims Fee	40	* 40	0	x \$9.00	0 x \$18.00	-0-
Independent Claims	3	** 3	0	x \$42.00	0 x \$84.00	-0-
Multiple Dependent Claims ***				\$140.00	\$280.00	
TOTAL FILING FEE						\$-0-
NO ADDITIONAL FEE REQUIRED ****	IF NO FEE REQUIRED, INSERT "0"					-0-
LIST INDEPENDENT CLAIMS: 1, 21, 40						
* IF HIGHEST NUMBER PREVIOUSLY PAID FOR IS 20 OR LESS, WRITE "20" IN COLUMN 3 ** IF HIGHEST NUMBER PREVIOUSLY PAID FOR IS 3 OR LESS, WRITE "3" IN COLUMN 3 *** PAY THIS FEE ONLY WHEN MULTIPLE DEPENDENT CLAIMS ARE ADDED FOR THE FIRST TIME **** IF NO FEE REQUIRED, ADDRESS ENVELOPE TO "BOX NON-FEE AMENDMENTS"						

- ___ Attached is our check for \$ to pay the fees calculated above.
___ A Petition for Extension of Time and the required fee are enclosed.
___ Other enclosures:

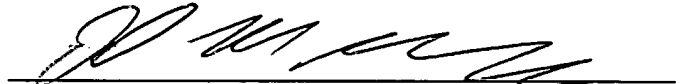
Amendment Transmittal Letter
Application No. 09/992,743

The Commissioner is hereby authorized to charge any fees under 37 CFR 1.16 and 1.17 which may be required by or to give effect to this paper to Deposit Account No. 03-1728. Please show our docket number with any charge or credit to our Deposit Account. **A copy of this letter is enclosed.**

Respectfully submitted,

CHRISTIE, PARKER & HALE, LLP

By



Daniel M. Cavanagh

Reg. No. 41,661

626/795-9900

DMC/rmw

RMW IRV1058253.1*-9/16/02 10:33 AM



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AMENDMENT

BOX NON-FEE AMENDMENT
Commissioner for Patents
Washington, D.C. 20231

Post Office Box 7068
Pasadena, CA 91109-7068
September 16, 2002

Commissioner:

In response to the Office action of June 16, 2002, please amend the above-identified application as follows:

In the Claims:

Please amend claims 1, 10, 20, 21 and 40 as follows:

Sub B1
1. (Amended) A treatment of a semiconductor device so as to allow substantially completely filled vias, the treatment comprising:

depositing a metal liner layer on a semiconductor device including an aperture;

depositing a seed layer of aluminum on the metal liner layer;

exposing the seed layer of aluminum to a reactive gas;
and